

IN THE CLAIMS

1. (original) A capacitor structure formed on a semiconductor substrate for providing capacitance between a first node and a second node comprising:

one or more layers of conductive strips, said conductive strips in each layer alternately connected to the first and second nodes, and

a conductive plate disposed beneath the lowest of the one or more layers of conductive strips.
2. (original) The capacitor structure of claim 1, wherein said conductive plate is connected to the first node.
3. (original) The capacitor structure of claim 1, wherein said conductive plate is connected to the second node.
4. (original) The capacitor structure of claim 1, wherein said conductive plate is connected to a third node.
5. (original) The capacitor structure of claim 1, wherein said conductive plate is connected to a reference voltage.
6. (original) The capacitor structure of claim 1, wherein said conductive plate is connected to ground.
7. (original) The capacitor structure of claim 1, wherein all of said conductive strips have the same width and spacing.

8. (original) The capacitor structure of claim 1, wherein the capacitor structure includes a plurality of layers of conductive strips.
9. (original) The capacitor structure of claim 8, wherein the plurality of layers of conductive strips are aligned so that strips connected to the first node lie above strips connected to the second node.
10. (original) The capacitor structure of claim 8, wherein the plurality of layers of conductive strips are aligned so that strips connected to the first node lie above strips connected to the first node.
11. (original) The capacitor structure of claim 1, further comprising a second conductive plate disposed above the highest of the one or more layers of conductive strips.
12. (original) The capacitor structure of claim 1, wherein said conductive plate is connected to the second node.
13. (original) The capacitor structure of claim 1, wherein said conductive plate is connected to the first node.
14. (original) The capacitor structure of claim 1, wherein said conductive plate is connected to a third node.
15. (original) The capacitor structure of claim 1, wherein said conductive plate is connected to a reference voltage.

16. (original) The capacitor structure of claim 1, wherein said conductive plate is connected to ground.

17. (original) The capacitor structure of claim 1, further comprising a second conductive plate disposed above the highest of the one or more layers of conductive strips, said conductive plate connected to the first node.

18. (original) The capacitor structure of claim 1, wherein the conductive plate is comprised of a solid planar conductive material.

19. (original) The capacitor structure of claim 1, wherein the conductive plate is comprised of a plurality of conductive strips connected to the first node.

20. (original) The capacitor structure of claim 1, further comprising a conducting side plate disposed to the side of the one or more layers of conductive strips.

Claims 21-52 (cancelled)